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Intel - EPM7160EQC160-12 Datasheet



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Understanding <u>Embedded - CPLDs (Complex</u> <u>Programmable Logic Devices)</u>

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixedfunction ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

Applications of Embedded - CPLDs

Details

Product Status	Obsolete
Programmable Type	EE PLD
Delay Time tpd(1) Max	12 ns
Voltage Supply - Internal	4.75V ~ 5.25V
Number of Logic Elements/Blocks	10
Number of Macrocells	160
Number of Gates	3200
Number of I/O	104
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	160-BQFP
Supplier Device Package	160-PQFP (28x28)
Purchase URL	https://www.e-xfl.com/product-detail/intel/epm7160eqc160-12

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	 Additional design entry and simulation support provided by EDIF 2 0 0 and 3 0 0 netlist files, library of parameterized modules (LPM), Verilog HDL, VHDL, and other interfaces to popular EDA tools from manufacturers such as Cadence, Exemplar Logic, Mentor Graphics, OrCAD, Synopsys, and VeriBest Programming support Altera's Master Programming Unit (MPU) and programming hardware from third-party manufacturers program all MAX 7000 devices The BitBlasterTM serial download cable, ByteBlasterMVTM parallel port download cable, and MasterBlasterTM serial/universal serial bus (USB) download cable program MAX 7000S devices
General Description	The MAX 7000 family of high-density, high-performance PLDs is based on Altera's second-generation MAX architecture. Fabricated with advanced CMOS technology, the EEPROM-based MAX 7000 family provides 600 to 5,000 usable gates, ISP, pin-to-pin delays as fast as 5 ns, and counter speeds of up to 175.4 MHz. MAX 7000S devices in the -5, -6, -7, and -10 speed grades as well as MAX 7000 and MAX 7000E devices in -5, -6, -7, -10P, and -12P speed grades comply with the PCI Special Interest Group (PCI SIG) <i>PCI Local Bus Specification, Revision 2.2.</i> See Table 3 for available speed grades.

Table 3. MA	Table 3. MAX 7000 Speed Grades											
Device					Speed	Grade						
	-5	-6	-7	-10P	-10	-12P	-12	-15	-15T	-20		
EPM7032		~	~		\checkmark		~	>	\checkmark			
EPM7032S	~	~	~		~							
EPM7064		~	~		~		~	\checkmark				
EPM7064S	\checkmark	~	~		~							
EPM7096			~		\checkmark		~	\checkmark				
EPM7128E			~	 	~		~	\checkmark		~		
EPM7128S		~	~		~			\checkmark				
EPM7160E				 Image: A start of the start of	~		~	~		~		
EPM7160S		 Image: A start of the start of	~		~			~				
EPM7192E						 Image: A set of the set of the	~	~		~		
EPM7192S			~		~			~				
EPM7256E						~	\checkmark	\checkmark		\checkmark		
EPM7256S			\checkmark		\checkmark			\checkmark				

The MAX 7000 architecture supports 100% TTL emulation and high-density integration of SSI, MSI, and LSI logic functions. The MAX 7000 architecture easily integrates multiple devices ranging from PALs, GALs, and 22V10s to MACH and pLSI devices. MAX 7000 devices are available in a wide range of packages, including PLCC, PGA, PQFP, RQFP, and TQFP packages. See Table 5.

Table 5. M.	Table 5. MAX 7000 Maximum User I/O Pins Note (1)												
Device	44- Pin PLCC	44- Pin PQFP	44- Pin TQFP	68- Pin PLCC	84- Pin PLCC	100- Pin PQFP	100- Pin TQFP	160- Pin PQFP	160- Pin PGA	192- Pin PGA	208- Pin PQFP	208- Pin RQFP	
EPM7032	36	36	36										
EPM7032S	36		36										
EPM7064	36		36	52	68	68							
EPM7064S	36		36		68		68						
EPM7096				52	64	76							
EPM7128E					68	84		100					
EPM7128S					68	84	84 (2)	100					
EPM7160E					64	84		104					
EPM7160S					64		84 (2)	104					
EPM7192E								124	124				
EPM7192S								124					
EPM7256E								132 (2)		164		164	
EPM7256S											164 (2)	164	

Notes:

 When the JTAG interface in MAX 7000S devices is used for either boundary-scan testing or for ISP, four I/O pins become JTAG pins.

(2) Perform a complete thermal analysis before committing a design to this device package. For more information, see the *Operating Requirements for Altera Devices Data Sheet*.

MAX 7000 devices use CMOS EEPROM cells to implement logic functions. The user-configurable MAX 7000 architecture accommodates a variety of independent combinatorial and sequential logic functions. The devices can be reprogrammed for quick and efficient iterations during design development and debug cycles, and can be programmed and erased up to 100 times.

The MAX 7000 architecture includes four dedicated inputs that can be used as general-purpose inputs or as high-speed, global control signals (clock, clear, and two output enable signals) for each macrocell and I/O pin. Figure 1 shows the architecture of EPM7032, EPM7064, and EPM7096 devices.



Figure 1. EPM7032, EPM7064 & EPM7096 Device Block Diagram

Each LAB is fed by the following signals:

- **3**6 signals from the PIA that are used for general logic inputs
- Global controls that are used for secondary register functions
- Direct input paths from I/O pins to the registers that are used for fast setup times for MAX 7000E and MAX 7000S devices

Macrocells

The MAX 7000 macrocell can be individually configured for either sequential or combinatorial logic operation. The macrocell consists of three functional blocks: the logic array, the product-term select matrix, and the programmable register. The macrocell of EPM7032, EPM7064, and EPM7096 devices is shown in Figure 3.

Figure 3. EPM7032, EPM7064 & EPM7096 Device Macrocell



Programming Times

The time required to implement each of the six programming stages can be broken into the following two elements:

- A pulse time to erase, program, or read the EEPROM cells.
- A shifting time based on the test clock (TCK) frequency and the number of TCK cycles to shift instructions, address, and data into the device.

By combining the pulse and shift times for each of the programming stages, the program or verify time can be derived as a function of the TCK frequency, the number of devices, and specific target device(s). Because different ISP-capable devices have a different number of EEPROM cells, both the total fixed and total variable times are unique for a single device.

Programming a Single MAX 7000S Device

The time required to program a single MAX 7000S device in-system can be calculated from the following formula:

$$t_{PROG} = t_{PPULSE} + \frac{Cycle_{PTCK}}{f_{TCK}}$$
where: t_{PROG} = Programming time
 t_{PPULSE} = Sum of the fixed times to erase, program, and
verify the EEPROM cells
 $Cycle_{PTCK}$ = Number of TCK cycles to program a device
 f_{TCK} = TCK frequency

The ISP times for a stand-alone verification of a single MAX 7000S device can be calculated from the following formula:

$$t_{VER} = t_{VPULSE} + \frac{Cycle_{VTCK}}{f_{TCK}}$$
where: t_{VER} = Verify time
 t_{VPULSE} = Sum of the fixed times to verify the EEPROM cells
 $Cycle_{VTCK}$ = Number of TCK cycles to verify a device

Programmable Speed/Power Control

MAX 7000 devices offer a power-saving mode that supports low-power operation across user-defined signal paths or the entire device. This feature allows total power dissipation to be reduced by 50% or more, because most logic applications require only a small fraction of all gates to operate at maximum frequency.

The designer can program each individual macrocell in a MAX 7000 device for either high-speed (i.e., with the Turbo BitTM option turned on) or low-power (i.e., with the Turbo Bit option turned off) operation. As a result, speed-critical paths in the design can run at high speed, while the remaining paths can operate at reduced power. Macrocells that run at low power incur a nominal timing delay adder (t_{LPA}) for the t_{LAD} , t_{LAC} , t_{IC} , t_{EN} , and t_{SEXP} , \mathbf{t}_{ACL} , and \mathbf{t}_{CPPW} parameters.

Output Configuration

MAX 7000 device outputs can be programmed to meet a variety of system-level requirements.

MultiVolt I/O Interface

MAX 7000 devices—except 44-pin devices—support the MultiVolt I/O interface feature, which allows MAX 7000 devices to interface with systems that have differing supply voltages. The 5.0-V devices in all packages can be set for 3.3-V or 5.0-V I/O pin operation. These devices have one set of VCC pins for internal operation and input buffers (VCCINT), and another set for I/O output drivers (VCCIO).

The VCCINT pins must always be connected to a 5.0-V power supply. With a 5.0-V V_{CCINT} level, input voltage thresholds are at TTL levels, and are therefore compatible with both 3.3-V and 5.0-V inputs.

The VCCIO pins can be connected to either a 3.3-V or a 5.0-V power supply, depending on the output requirements. When the VCCIO pins are connected to a 5.0-V supply, the output levels are compatible with 5.0-V systems. When V_{CCIO} is connected to a 3.3-V supply, the output high is 3.3 V and is therefore compatible with 3.3-V or 5.0-V systems. Devices operating with V_{CCIO} levels lower than 4.75 V incur a nominally greater timing delay of t_{OD2} instead of t_{OD1} .

Open-Drain Output Option (MAX 7000S Devices Only)

MAX 7000S devices provide an optional open-drain (functionally equivalent to open-collector) output for each I/O pin. This open-drain output enables the device to provide system-level control signals (e.g., interrupt and write enable signals) that can be asserted by any of several devices. It can also provide an additional wired-OR plane.

By using an external 5.0-V pull-up resistor, output pins on MAX 7000S devices can be set to meet 5.0-V CMOS input voltages. When V_{CCIO} is 3.3 V, setting the open drain option will turn off the output pull-up transistor, allowing the external pull-up resistor to pull the output high enough to meet 5.0-V CMOS input voltages. When V_{CCIO} is 5.0 V, setting the output drain option is not necessary because the pull-up transistor will already turn off when the pin exceeds approximately 3.8 V, allowing the external pull-up resistor to pull the output high enough to meet 5.0-V CMOS input voltages.

Slew-Rate Control

The output buffer for each MAX 7000E and MAX 7000S I/O pin has an adjustable output slew rate that can be configured for low-noise or high-speed performance. A faster slew rate provides high-speed transitions for high-performance systems. However, these fast transitions may introduce noise transients into the system. A slow slew rate reduces system noise, but adds a nominal delay of 4 to 5 ns. In MAX 7000E devices, when the Turbo Bit is turned off, the slew rate is set for low noise performance. For MAX 7000S devices, each I/O pin has an individual EEPROM bit that controls the slew rate, allowing designers to specify the slew rate on a pin-by-pin basis.

MAX 7000 devices can be programmed on Windows-based PCs with the Altera Logic Programmer card, the Master Programming Unit (MPU), and the appropriate device adapter. The MPU performs a continuity check to ensure adequate electrical contact between the adapter and the device.

For more information, see the *Altera Programming Hardware Data Sheet*.

The Altera development system can use text- or waveform-format test vectors created with the Text Editor or Waveform Editor to test the programmed device. For added design verification, designers can perform functional testing to compare the functional behavior of a MAX 7000 device with the results of simulation. Moreover, Data I/O, BP Microsystems, and other programming hardware manufacturers also provide programming support for Altera devices.



For more information, see the Programming Hardware Manufacturers.

Programming with External Hardware

IEEE Std. 1149.1 (JTAG) Boundary-Scan Support

MAX 7000 devices support JTAG BST circuitry as specified by IEEE Std. 1149.1-1990. Table 9 describes the JTAG instructions supported by the MAX 7000 family. The pin-out tables (see the Altera web site (http://www.altera.com) or the *Altera Digital Library* for pin-out information) show the location of the JTAG control pins for each device. If the JTAG interface is not required, the JTAG pins are available as user I/O pins.

Table 9. MAX 7000 J	ITAG Instructions	3
JTAG Instruction	Devices	Description
SAMPLE/PRELOAD	EPM7128S EPM7160S EPM7192S EPM7256S	Allows a snapshot of signals at the device pins to be captured and examined during normal device operation, and permits an initial data pattern output at the device pins.
EXTEST	EPM7128S EPM7160S EPM7192S EPM7256S	Allows the external circuitry and board-level interconnections to be tested by forcing a test pattern at the output pins and capturing test results at the input pins.
BYPASS	EPM7032S EPM7064S EPM7128S EPM7160S EPM7192S EPM7256S	Places the 1-bit bypass register between the TDI and TDO pins, which allows the BST data to pass synchronously through a selected device to adjacent devices during normal device operation.
IDCODE	EPM7032S EPM7064S EPM7128S EPM7160S EPM7192S EPM7256S	Selects the IDCODE register and places it between TDI and TDO, allowing the IDCODE to be serially shifted out of TDO.
ISP Instructions	EPM7032S EPM7064S EPM7128S EPM7160S EPM7192S EPM7256S	These instructions are used when programming MAX 7000S devices via the JTAG ports with the MasterBlaster, ByteBlasterMV, BitBlaster download cable, or using a Jam File (.jam), Jam Byte-Code file (.jbc), or Serial Vector Format file (.svf) via an embedded processor or test equipment.

The instruction register length of MAX 7000S devices is 10 bits. Tables 10 and 11 show the boundary-scan register length and device IDCODE information for MAX 7000S devices.

Table 10. MAX 7000S Boundary-Scan Register Length									
Device	Boundary-Scan Register Length								
EPM7032S	1 (1)								
EPM7064S	1 (1)								
EPM7128S	288								
EPM7160S	312								
EPM7192S	360								
EPM7256S	480								

Note:

 This device does not support JTAG boundary-scan testing. Selecting either the EXTEST or SAMPLE/PRELOAD instruction will select the one-bit bypass register.

Table 11. 32-Bit MAX 7000 Device IDCODE Note (1)											
Device		IDCODE (32 B	lits)								
	Version (4 Bits)	Part Number (16 Bits)	Manufacturer's Identity (11 Bits)	1 (1 Bit) (2)							
EPM7032S	0000	0111 0000 0011 0010	00001101110	1							
EPM7064S	0000	0111 0000 0110 0100	00001101110	1							
EPM7128S	0000	0111 0001 0010 1000	00001101110	1							
EPM7160S	0000	0111 0001 0110 0000	00001101110	1							
EPM7192S	0000	0111 0001 1001 0010	00001101110	1							
EPM7256S	0000	0111 0010 0101 0110	00001101110	1							

Notes:

(1) The most significant bit (MSB) is on the left.

(2) The least significant bit (LSB) for all JTAG IDCODEs is 1.

Symbol	Parameter	Conditions		Speed	Grade		Unit
e ye			MAX 700	00E (-10P)	MAX 70	00 (-10) 00E (-10)	•
			Min	Max	Min	Max	
t _{IN}	Input pad and buffer delay			0.5		1.0	ns
t _{IO}	I/O input pad and buffer delay			0.5		1.0	ns
t _{FIN}	Fast input delay	(2)		1.0		1.0	ns
t _{SEXP}	Shared expander delay			5.0		5.0	ns
t _{PEXP}	Parallel expander delay			0.8		0.8	ns
t _{LAD}	Logic array delay			5.0		5.0	ns
t _{LAC}	Logic control array delay			5.0		5.0	ns
t _{IOE}	Internal output enable delay	(2)		2.0		2.0	ns
t _{OD1}	Output buffer and pad delay Slow slew rate = off $V_{CCIO} = 5.0 V$	C1 = 35 pF		1.5		2.0	ns
t _{OD2}	Output buffer and pad delay Slow slew rate = off V _{CCIO} = 3.3 V	C1 = 35 pF (7)		2.0		2.5	ns
t _{OD3}	Output buffer and pad delay Slow slew rate = on V _{CCIO} = 5.0 V or 3.3 V	C1 = 35 pF <i>(</i> 2 <i>)</i>		5.5		6.0	ns
t _{ZX1}	Output buffer enable delay Slow slew rate = off $V_{CCIO} = 5.0 V$	C1 = 35 pF		5.0		5.0	ns
t _{ZX2}	Output buffer enable delay Slow slew rate = off $V_{CCIO} = 3.3 V$	C1 = 35 pF (7)		5.5		5.5	ns
t _{ZX3}	Output buffer enable delay Slow slew rate = on $V_{CCIO} = 5.0 V \text{ or } 3.3 V$	C1 = 35 pF <i>(</i> 2 <i>)</i>		9.0		9.0	ns
t _{XZ}	Output buffer disable delay	C1 = 5 pF		5.0		5.0	ns
t _{SU}	Register setup time		2.0		3.0		ns
t _H	Register hold time		3.0		3.0		ns
t _{FSU}	Register setup time of fast input	(2)	3.0		3.0		ns
t _{FH}	Register hold time of fast input	(2)	0.5		0.5		ns
t _{RD}	Register delay			2.0		1.0	ns
t _{COMB}	Combinatorial delay			2.0		1.0	ns
t _{IC}	Array clock delay			5.0		5.0	ns
t _{EN}	Register enable time			5.0		5.0	ns
t _{GLOB}	Global control delay			1.0		1.0	ns
t _{PRE}	Register preset time			3.0		3.0	ns
t _{CLR}	Register clear time			3.0		3.0	ns
t _{PIA}	PIA delay			1.0		1.0	ns
t _{LPA}	Low-power adder	(8)		11.0		11.0	ns

Symbol	Parameter	Conditions		Speed	Grade		Unit	
			MAX 700	IOE (-12P)	MAX 70 Max 70	100 (-12) Doe (-12)		
			Min	Max	Min	Max		
t _{IN}	Input pad and buffer delay			1.0		2.0	ns	
t _{IO}	I/O input pad and buffer delay			1.0		2.0	ns	
t _{FIN}	Fast input delay	(2)		1.0		1.0	ns	
t _{SEXP}	Shared expander delay			7.0		7.0	ns	
t _{PEXP}	Parallel expander delay			1.0		1.0	ns	
t _{LAD}	Logic array delay			7.0		5.0	ns	
t _{LAC}	Logic control array delay			5.0		5.0	ns	
t _{IOE}	Internal output enable delay	(2)		2.0		2.0	ns	
t _{OD1}	Output buffer and pad delay Slow slew rate = off V _{CCIO} = 5.0 V	C1 = 35 pF		1.0		3.0	ns	
t _{OD2}	Output buffer and pad delay Slow slew rate = off V _{CCIO} = 3.3 V	C1 = 35 pF (7)		2.0		4.0	ns	
t _{OD3}	Output buffer and pad delay Slow slew rate = on V _{CCIO} = 5.0 V or 3.3 V	C1 = 35 pF (2)		5.0		7.0	ns	
t _{ZX1}	Output buffer enable delay Slow slew rate = off $V_{CCIO} = 5.0 V$	C1 = 35 pF		6.0		6.0	ns	
t _{ZX2}	Output buffer enable delay Slow slew rate = off $V_{CCIO} = 3.3 V$	C1 = 35 pF (7)		7.0		7.0	ns	
t _{ZX3}	Output buffer enable delay Slow slew rate = on $V_{CCIO} = 5.0 V \text{ or } 3.3 V$	C1 = 35 pF (2)		10.0		10.0	ns	
t _{XZ}	Output buffer disable delay	C1 = 5 pF		6.0		6.0	ns	
t _{SU}	Register setup time		1.0		4.0		ns	
t _H	Register hold time		6.0		4.0		ns	
t _{FSU}	Register setup time of fast input	(2)	4.0		2.0		ns	
t _{FH}	Register hold time of fast input	(2)	0.0		2.0		ns	
t _{RD}	Register delay			2.0		1.0	ns	
t _{COMB}	Combinatorial delay			2.0		1.0	ns	
t _{IC}	Array clock delay			5.0		5.0	ns	
t _{EN}	Register enable time			7.0		5.0	ns	
t _{GLOB}	Global control delay			2.0		0.0	ns	
t _{PRE}	Register preset time			4.0		3.0	ns	
t _{CLR}	Register clear time			4.0		3.0	ns	
t _{PIA}	PIA delay			1.0		1.0	ns	
t _{LPA}	Low-power adder	(8)		12.0		12.0	ns	

Table 27. EPM7032S External Timing Parameters (Part 2 of 2) Note (1)											
Symbol	Parameter	Conditions				Speed	Grade				Unit
			-	-5 -6			6 -7		-10		
			Min	Max	Min	Max	Min	Max	Min	Max	
f _{ACNT}	Maximum internal array clock frequency	(4)	175.4		142.9		116.3		100.0		MHz
f _{MAX}	Maximum clock frequency	(5)	250.0		200.0		166.7		125.0		MHz

Symbol	Parameter	Conditions	Speed Grade									
			-	-5		-6		-7		-10		
			Min	Max	Min	Max	Min	Max	Min	Max		
t _{IN}	Input pad and buffer delay			0.2		0.2		0.3		0.5	ns	
t _{IO}	I/O input pad and buffer delay			0.2		0.2		0.3		0.5	ns	
t _{FIN}	Fast input delay			2.2		2.1		2.5		1.0	ns	
t _{SEXP}	Shared expander delay			3.1		3.8		4.6		5.0	ns	
t _{PEXP}	Parallel expander delay			0.9		1.1		1.4		0.8	ns	
t _{LAD}	Logic array delay			2.6		3.3		4.0		5.0	ns	
t _{LAC}	Logic control array delay			2.5		3.3		4.0		5.0	ns	
t _{IOE}	Internal output enable delay			0.7		0.8		1.0		2.0	ns	
t _{OD1}	Output buffer and pad delay	C1 = 35 pF		0.2		0.3		0.4		1.5	ns	
t _{OD2}	Output buffer and pad delay	C1 = 35 pF (6)		0.7		0.8		0.9		2.0	ns	
t _{OD3}	Output buffer and pad delay	C1 = 35 pF		5.2		5.3		5.4		5.5	ns	
t _{ZX1}	Output buffer enable delay	C1 = 35 pF		4.0		4.0		4.0		5.0	ns	
t _{ZX2}	Output buffer enable delay	C1 = 35 pF (6)		4.5		4.5		4.5		5.5	ns	
t _{ZX3}	Output buffer enable delay	C1 = 35 pF		9.0		9.0		9.0		9.0	ns	
t _{XZ}	Output buffer disable delay	C1 = 5 pF		4.0		4.0		4.0		5.0	ns	
t _{SU}	Register setup time		0.8		1.0		1.3		2.0		ns	
t _H	Register hold time		1.7		2.0		2.5		3.0		ns	
t _{FSU}	Register setup time of fast input		1.9		1.8		1.7		3.0		ns	
t _{FH}	Register hold time of fast input		0.6		0.7		0.8		0.5		ns	
t _{RD}	Register delay			1.2		1.6		1.9		2.0	ns	
t _{COMB}	Combinatorial delay			0.9		1.1		1.4		2.0	ns	
t _{IC}	Array clock delay			2.7		3.4		4.2		5.0	ns	
t _{EN}	Register enable time			2.6		3.3		4.0		5.0	ns	
t _{GLOB}	Global control delay			1.6		1.4		1.7		1.0	ns	
t _{PRE}	Register preset time			2.0		2.4		3.0		3.0	ns	
t _{CLR}	Register clear time			2.0		2.4		3.0		3.0	ns	

Table 28. EPM7032S Internal Timing Parameters Note (1)												
Symbol	Parameter	Conditions				Speed	Grade				Unit	
			-5 -6		-7		-10					
			Min	Max	Min	Max	Min	Max	Min	Max		
t _{PIA}	PIA delay	(7)		1.1		1.1		1.4		1.0	ns	
t _{LPA}	Low-power adder	(8)		12.0		10.0		10.0		11.0	ns	

Notes to tables:

- (1) These values are specified under the recommended operating conditions shown in Table 14. See Figure 13 for more information on switching waveforms.
- (2) This minimum pulse width for preset and clear applies for both global clear and array controls. The t_{LPA} parameter must be added to this minimum width if the clear or reset signal incorporates the t_{LAD} parameter into the signal path.
- (3) This parameter is a guideline that is sample-tested only and is based on extensive device characterization. This parameter applies for both global and array clocking.
- (4) These parameters are measured with a 16-bit loadable, enabled, up/down counter programmed into each LAB.
- (5) The f_{MAX} values represent the highest frequency for pipelined data.
- (6) Operating conditions: $V_{CCIO} = 3.3 \text{ V} \pm 10\%$ for commercial and industrial use.
- (7) For EPM7064S-5, EPM7064S-6, EPM7128S-6, EPM7160S-6, EPM7160S-7, EPM7192S-7, and EPM7256S-7 devices, these values are specified for a PIA fan-out of one LAB (16 macrocells). For each additional LAB fan-out in these devices, add an additional 0.1 ns to the PIA timing value.
- (8) The t_{LPA} parameter must be added to the t_{LAD} , t_{LAC} , t_{IC} , t_{EN} , t_{SEXP} , t_{ACL} , and t_{CPPW} parameters for macrocells running in the low-power mode.

Tables 29 and 30 show the EPM7064S AC operating conditions.

Table 2	Table 29. EPM7064S External Timing Parameters (Part 1 of 2)Note (1)											
Symbol	Parameter	Conditions Speed Grade										
			-	5	-	6	-	7	-1	0		
			Min	Max	Min	Max	Min	Max	Min	Max		
t _{PD1}	Input to non-registered output	C1 = 35 pF		5.0		6.0		7.5		10.0	ns	
t _{PD2}	I/O input to non-registered output	C1 = 35 pF		5.0		6.0		7.5		10.0	ns	
t _{SU}	Global clock setup time		2.9		3.6		6.0		7.0		ns	
t _H	Global clock hold time		0.0		0.0		0.0		0.0		ns	
t _{FSU}	Global clock setup time of fast input		2.5		2.5		3.0		3.0		ns	
t _{FH}	Global clock hold time of fast input		0.0		0.0		0.5		0.5		ns	
t _{CO1}	Global clock to output delay	C1 = 35 pF		3.2		4.0		4.5		5.0	ns	
t _{CH}	Global clock high time		2.0		2.5		3.0		4.0		ns	
t _{CL}	Global clock low time		2.0		2.5		3.0		4.0		ns	
t _{ASU}	Array clock setup time		0.7		0.9		3.0		2.0		ns	
t _{AH}	Array clock hold time		1.8		2.1		2.0		3.0		ns	

Table 29. EPM7064S External Timing Parameters (Part 2 of 2) Note (1)											
Symbol	Parameter	Conditions			Unit						
			-	5	-	6	-	7	-1	0	
			Min	Max	Min	Max	Min	Max	Min	Max	
t _{ACO1}	Array clock to output delay	C1 = 35 pF		5.4		6.7		7.5		10.0	ns
t _{ACH}	Array clock high time		2.5		2.5		3.0		4.0		ns
t _{ACL}	Array clock low time		2.5		2.5		3.0		4.0		ns
t _{CPPW}	Minimum pulse width for clear and preset	(2)	2.5		2.5		3.0		4.0		ns
t _{ODH}	Output data hold time after clock	C1 = 35 pF (3)	1.0		1.0		1.0		1.0		ns
t _{CNT}	Minimum global clock period			5.7		7.1		8.0		10.0	ns
f _{CNT}	Maximum internal global clock frequency	(4)	175.4		140.8		125.0		100.0		MHz
t _{ACNT}	Minimum array clock period			5.7		7.1		8.0		10.0	ns
f _{ACNT}	Maximum internal array clock frequency	(4)	175.4		140.8		125.0		100.0		MHz
f _{MAX}	Maximum clock frequency	(5)	250.0		200.0		166.7		125.0		MHz

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 Table 30. EPM7064S Internal Timing Parameters (Part 1 of 2)

 Note (1)

Symbol	Parameter	Conditions	Speed Grade								Unit
			-	5	-	-6 -7		-10		1	
			Min	Max	Min	Max	Min	Max	Min	Max	1
t _{IN}	Input pad and buffer delay			0.2		0.2		0.5		0.5	ns
t _{IO}	I/O input pad and buffer delay			0.2		0.2		0.5		0.5	ns
t _{FIN}	Fast input delay			2.2		2.6		1.0		1.0	ns
t _{SEXP}	Shared expander delay			3.1		3.8		4.0		5.0	ns
t _{PEXP}	Parallel expander delay			0.9		1.1		0.8		0.8	ns
t _{LAD}	Logic array delay			2.6		3.2		3.0		5.0	ns
t _{LAC}	Logic control array delay			2.5		3.2		3.0		5.0	ns
t _{IOE}	Internal output enable delay			0.7		0.8		2.0		2.0	ns
t _{OD1}	Output buffer and pad delay	C1 = 35 pF		0.2		0.3		2.0		1.5	ns
t _{OD2}	Output buffer and pad delay	C1 = 35 pF (6)		0.7		0.8		2.5		2.0	ns
t _{OD3}	Output buffer and pad delay	C1 = 35 pF		5.2		5.3		7.0		5.5	ns
t _{ZX1}	Output buffer enable delay	C1 = 35 pF		4.0		4.0		4.0		5.0	ns
t _{ZX2}	Output buffer enable delay	C1 = 35 pF (6)		4.5		4.5		4.5		5.5	ns
t _{ZX3}	Output buffer enable delay	C1 = 35 pF		9.0		9.0		9.0		9.0	ns
t _{XZ}	Output buffer disable delay	C1 = 5 pF		4.0		4.0		4.0		5.0	ns
t _{SU}	Register setup time		0.8		1.0		3.0		2.0		ns
t _H	Register hold time		1.7		2.0		2.0		3.0		ns

Table 33. EPM7160S External Timing Parameters (Part 2 of 2) Note (1)											
Symbol	Parameter	Conditions	Speed Grade							Unit	
			-	-6 -7 -10				-1	5		
			Min	Max	Min	Max	Min	Max	Min	Max	
t _{ACNT}	Minimum array clock period			6.7		8.2		10.0		13.0	ns
facnt	Maximum internal array clock frequency	(4)	149.3		122.0		100.0		76.9		MHz
f _{MAX}	Maximum clock frequency	(5)	166.7		166.7		125.0		100.0		MHz

Symbol	Parameter	Conditions	Speed Grade								Unit
			-6		-	7	-10		-15]
			Min	Max	Min	Max	Min	Max	Min	Max	
t _{IN}	Input pad and buffer delay			0.2		0.3		0.5		2.0	ns
t _{IO}	I/O input pad and buffer delay			0.2		0.3		0.5		2.0	ns
t _{FIN}	Fast input delay			2.6		3.2		1.0		2.0	ns
t _{SEXP}	Shared expander delay			3.6		4.3		5.0		8.0	ns
t _{PEXP}	Parallel expander delay			1.0		1.3		0.8		1.0	ns
t _{LAD}	Logic array delay			2.8		3.4		5.0		6.0	ns
t _{LAC}	Logic control array delay			2.8		3.4		5.0		6.0	ns
t _{IOE}	Internal output enable delay			0.7		0.9		2.0		3.0	ns
t _{OD1}	Output buffer and pad delay	C1 = 35 pF		0.4		0.5		1.5		4.0	ns
t _{OD2}	Output buffer and pad delay	C1 = 35 pF (6)		0.9		1.0		2.0		5.0	ns
t _{OD3}	Output buffer and pad delay	C1 = 35 pF		5.4		5.5		5.5		8.0	ns
t _{ZX1}	Output buffer enable delay	C1 = 35 pF		4.0		4.0		5.0		6.0	ns
t _{ZX2}	Output buffer enable delay	C1 = 35 pF (6)		4.5		4.5		5.5		7.0	ns
t _{ZX3}	Output buffer enable delay	C1 = 35 pF		9.0		9.0		9.0		10.0	ns
t _{XZ}	Output buffer disable delay	C1 = 5 pF		4.0		4.0		5.0		6.0	ns
t _{SU}	Register setup time		1.0		1.2		2.0		4.0		ns
t _H	Register hold time		1.6		2.0		3.0		4.0		ns
t _{FSU}	Register setup time of fast input		1.9		2.2		3.0		2.0		ns
t _{FH}	Register hold time of fast input		0.6		0.8		0.5		1.0		ns
t _{RD}	Register delay			1.3		1.6		2.0		1.0	ns
t _{COMB}	Combinatorial delay			1.0		1.3		2.0		1.0	ns
t _{IC}	Array clock delay			2.9		3.5		5.0		6.0	ns
t _{EN}	Register enable time			2.8		3.4		5.0		6.0	ns
t _{GLOB}	Global control delay			2.0		2.4		1.0		1.0	ns
t _{PRF}	Register preset time			2.4		3.0		3.0		4.0	ns

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Table 38. EPM7256S Internal Timing Parameters Note (1)										
Symbol	Parameter	Conditions			Unit					
			-	7	-10		-10 -1			
			Min	Max	Min	Max	Min	Max		
t _{IN}	Input pad and buffer delay			0.3		0.5		2.0	ns	
t _{IO}	I/O input pad and buffer delay			0.3		0.5		2.0	ns	
t _{FIN}	Fast input delay			3.4		1.0		2.0	ns	
t _{SEXP}	Shared expander delay			3.9		5.0		8.0	ns	
t _{PEXP}	Parallel expander delay			1.1		0.8		1.0	ns	
t _{LAD}	Logic array delay			2.6		5.0		6.0	ns	
t _{LAC}	Logic control array delay			2.6		5.0		6.0	ns	
t _{IOE}	Internal output enable delay			0.8		2.0		3.0	ns	
t _{OD1}	Output buffer and pad delay	C1 = 35 pF		0.5		1.5		4.0	ns	
t _{OD2}	Output buffer and pad delay	C1 = 35 pF (6)		1.0		2.0		5.0	ns	
t _{OD3}	Output buffer and pad delay	C1 = 35 pF		5.5		5.5		8.0	ns	
t _{ZX1}	Output buffer enable delay	C1 = 35 pF		4.0		5.0		6.0	ns	
t _{ZX2}	Output buffer enable delay	C1 = 35 pF (6)		4.5		5.5		7.0	ns	
t _{ZX3}	Output buffer enable delay	C1 = 35 pF		9.0		9.0		10.0	ns	
t _{XZ}	Output buffer disable delay	C1 = 5 pF		4.0		5.0		6.0	ns	
t _{SU}	Register setup time		1.1		2.0		4.0		ns	
t _H	Register hold time		1.6		3.0		4.0		ns	
t _{FSU}	Register setup time of fast input		2.4		3.0		2.0		ns	
t _{FH}	Register hold time of fast input		0.6		0.5		1.0		ns	
t _{RD}	Register delay			1.1		2.0		1.0	ns	
t _{COMB}	Combinatorial delay			1.1		2.0		1.0	ns	
t _{IC}	Array clock delay			2.9		5.0		6.0	ns	
t _{EN}	Register enable time			2.6		5.0		6.0	ns	
t _{GLOB}	Global control delay			2.8		1.0		1.0	ns	
t _{PRE}	Register preset time			2.7		3.0		4.0	ns	
t _{CLR}	Register clear time			2.7		3.0		4.0	ns	
t _{PIA}	PIA delay	(7)		3.0		1.0		2.0	ns	
t _{LPA}	Low-power adder	(8)		10.0		11.0		13.0	ns	

Table 39. MAX 7000 I _{CC} Equation Constants										
Device	Α	В	C							
EPM7032	1.87	0.52	0.144							
EPM7064	1.63	0.74	0.144							
EPM7096	1.63	0.74	0.144							
EPM7128E	1.17	0.54	0.096							
EPM7160E	1.17	0.54	0.096							
EPM7192E	1.17	0.54	0.096							
EPM7256E	1.17	0.54	0.096							
EPM7032S	0.93	0.40	0.040							
EPM7064S	0.93	0.40	0.040							
EPM7128S	0.93	0.40	0.040							
EPM7160S	0.93	0.40	0.040							
EPM7192S	0.93	0.40	0.040							
EPM7256S	0.93	0.40	0.040							

This calculation provides an I_{CC} estimate based on typical conditions using a pattern of a 16-bit, loadable, enabled, up/down counter in each LAB with no output load. Actual I_{CC} values should be verified during operation because this measurement is sensitive to the actual pattern in the device and the environmental operating conditions.



Figure 15. I_{CC} vs. Frequency for MAX 7000S Devices (Part 2 of 2)

Device Pin-Outs

See the Altera web site (http://www.altera.com) or the *Altera Digital Library* for pin-out information.

Figure 19. 100-Pin Package Pin-Out Diagram

Package outline not drawn to scale.



Figure 20. 160-Pin Package Pin-Out Diagram

Package outline not drawn to scale.



Revision History

The information contained in the *MAX 7000 Programmable Logic Device Family Data Sheet* version 6.7 supersedes information published in previous versions. The following changes were made in the *MAX 7000 Programmable Logic Device Family Data Sheet* version 6.7:

Version 6.7

The following changes were made in the *MAX* 7000 *Programmable Logic Device Family Data Sheet* version 6.7:

Reference to AN 88: Using the Jam Language for ISP & ICR via an Embedded Processor has been replaced by AN 122: Using Jam STAPL for ISP & ICR via an Embedded Processor.

Version 6.6

The following changes were made in the *MAX* 7000 *Programmable Logic Device Family Data Sheet* version 6.6:

- Added Tables 6 through 8.
- Added "Programming Sequence" section on page 17 and "Programming Times" section on page 18.

Version 6.5

The following changes were made in the *MAX* 7000 *Programmable Logic Device Family Data Sheet* version 6.5:

Updated text on page 16.

Version 6.4

The following changes were made in the *MAX* 7000 Programmable Logic Device Family Data Sheet version 6.4:

Added Note (5) on page 28.

Version 6.3

The following changes were made in the *MAX* 7000 *Programmable Logic Device Family Data Sheet* version 6.3:

 Updated the "Open-Drain Output Option (MAX 7000S Devices Only)" section on page 20.